

REMARKS

Applicants request favorable reconsideration and allowance of the subject application in view of the preceding amendments and the following remarks.

Claims 1-34 are presented for consideration. Claims 1, 4, 7, 11, 14 and 18 are independent.

Claims 8 and 9 have been amended to clarify features of the subject invention, while claims 23-34 have been added to recite additional features of the subject invention. Support for these changes can be found in the original application, as filed. Therefore, no new matter has been added.

In the above-noted Office Action, the Examiner asserted that the rejection under 35 U.S.C. § 112, second paragraph, of claims 8 and 9, as set forth in the Office Action mailed April 6, 1999, were not addressed in Applicants' response filed October 6, 1999. Without conceding the propriety of this contention, Applicants have amended claims 8 and 9 herein. Specifically, claim 8 recites that the method recited in claim 7 further comprises forming an electrode line on the substrate, wherein the electrode layer is formed by a same material as that of the electrode line formed on the substrate. Claim 9 defines

that the method recited in claim 7 further comprises forming an electrode line on the substrate and simultaneously forming the electrode layer with the electrode line formed on the substrate.

For clarification, but not limitation, Applicants provide the following comments.

Original claim 7 defined that the slice line and the guide line defined in claim 1 were formed by electrode layers. The electrode layer is typically a layer for forming an electrode of a device and generally means, for example, a conductive layer of aluminum. In other words, claim 7 defines that the slice line and the guide line are formed using an electrode layer for forming a device.

However, since it is not necessary that the electrode layer always be used for an electrode line connected to a device (or a wiring) or for an electrode of a device formed on a substrate, the term "electrode layer" is used. Thus, the term "electrode layer" be considered to be synonymous with a conductive layer.

Original claim 8 defined that the electrode line formed on a substrate, which is an electrode line connected to one or more devices of an apparatus, is formed by a same material as that of the electrode layer. Original claim 9 defined that

the electrode layer and the electrode line are formed simultaneously. Thus, claim 8 defines that the electrode layer constitutes an electrode line to be provided on the substrate, whereas claim 9 defines that the electrode layer and the electrode line to be provided on the substrate are formed by, for example, patterning a conductive film such as a vapor-deposited film having simultaneously formed the electrode layer and the electrode line.

Applicant submits that the cited art does not teach or suggest such features of the present invention, as recited in claims 8 and 9. Therefore, those claims should be deemed allowable over the cited art.

In addition to claims 8 and 9 being allowable, Applicants submit that new claims 23-34 patentably define features of the subject invention. These claims correspond to examples 3, 4 and 5 in the original disclosure. Applicants submit that the cited art does not teach or suggest such features of the present invention cited in these claims, in which, for example, a first monitor line and/or a second monitor line interpose the slice line. Therefore, these claims likewise should be deemed allowable over the cited art.

Applicants submit that the instant application is in condition for allowance. Favorable reconsideration, withdrawal of the rejections set forth in the Office Action dated April 6, 1999, and an early Notice of Allowance are requested.

Applicants' undersigned attorney may be reached in our Washington, D.C. office by telephone at (202) 530-1010. All correspondence should be directed to our address listed below.

Respectfully submitted,

Stephan E. Elshour
Attorney for Applicants
Registration No. 33,326

FITZPATRICK, CELLA, HARPER & SCINTO
30 Rockefeller Plaza
New York, New York 10112-3801
Facsimile: (212) 218-2200

SEW\vjw